

Title (en)

INDIUM ELECTROPLATING COMPOSITIONS AND METHODS FOR ELECTROPLATING INDIUM

Title (de)

INDIUM-ELEKTROPLATTIERUNGSZUSAMMENSETZUNGEN UND INDIUM-ELEKTROPLATTIERUNGSVERFAHREN

Title (fr)

COMPOSITIONS ET PROCÉDÉS D'ÉLECTRODÉPOSITION D'INDIUM

Publication

**EP 3272909 A1 20180124 (EN)**

Application

**EP 17181550 A 20170714**

Priority

US 201615212713 A 20160718

Abstract (en)

Indium electroplating compositions electroplate substantially defect-free uniform layers which have a smooth surface morphology on metal layers. The indium electroplating compositions can be used to electroplate indium metal on metal layers of various substrates such as semiconductor wafers and as thermal interface materials.

IPC 8 full level

**C25D 3/54** (2006.01)

CPC (source: EP KR US)

**C25D 3/54** (2013.01 - EP KR US); **C25D 7/123** (2013.01 - KR); **C25D 5/611** (2020.08 - KR)

Citation (search report)

- [XAYI] US 2008173550 A1 20080724 - KISO MASAYUKI [JP], et al
- [XAI] EP 1978051 A1 20081008 - ROHM & HAAS ELECT MAT [US]
- [X] US 2012055612 A1 20120308 - AHMED SHAFAT [US], et al
- [X] EP 1544164 A2 20050622 - DALSA SEMICONDUCTOR INC [CA]
- [IY] SU 222104 A1 19691007

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

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**EP 3272909 A1 20180124**; **EP 3272909 B1 20190403**; CN 107630238 A 20180126; CN 107630238 B 20190827; JP 2018012886 A 20180125; JP 6442001 B2 20181219; KR 102022926 B1 20190919; KR 20180009310 A 20180126; TW 201804023 A 20180201; TW I639735 B 20181101; US 2018016689 A1 20180118

DOCDB simple family (application)

**EP 17181550 A 20170714**; CN 201710512994 A 20170629; JP 2017123892 A 20170626; KR 20170084616 A 20170704; TW 106120952 A 20170622; US 201615212713 A 20160718